

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Changes to test conditions in table I. Change code ident. no. from 14933 to 67268. Editorial changes throughout.	87-11-24	R. P. Evans
B	Add generic part number 1691A. Changes to table I. Editorial changes throughout.	94-10-05	M. A. Frye

THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

REV																			
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REV STATUS OF SHEETS	REV	B	B	B	B	B	B	B	B	B	B	B	B	B	B	B	B	B	B
	SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13	14				

STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A	PREPARED BY Donald R. Osborne	DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		
	CHECKED BY D. A. DiCenzo			
	APPROVED BY N. A. Hauck	MICROCIRCUIT, LINEAR, RS-422/RS-433 LINE DRIVER, MONOLITHIC SILICON		
	DRAWING APPROVAL DATE 86-12-31			
	REVISION LEVEL B	SIZE A	CAGE CODE 67268	5962-86721
	SHEET 1 OF 14			

DESC FORM 193
JUL 94

5962-E423-94

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

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1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part or Identifying Number (PIN). The complete PIN shall be as shown in the following example:



1.2.1 Device type(s). The device type(s) shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	26LS30, 1691A	Dual differential RS-422 party line/quad single ended RS-423 line driver

1.2.2 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
E	CDIP1-T16 or GDIP2-T16	16	Dual-in-line
F	CDFP3-F16 or GDFP2-F16	16	Flat pack
Z	CQCC1-N20	20	Square leadless chip carrier

1.2.3 Lead finish. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein). Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

1.3 Absolute maximum ratings.

Supply voltage range (V_{CC})	- - - - -	-0.5 V dc to +7.0 V dc
Supply voltage range (V_{EE})	- - - - -	+0.5 V dc to -7.0 V dc
Input voltage range	- - - - -	-1.5 V dc to +15.0 V dc
Storage temperature range	- - - - -	-65°C to +150°C
Maximum power dissipation (P_D) ^{1/}	- - - - -	500 mW
Lead temperature (soldering, 4 seconds)	- - - - -	+260°C
Thermal resistance, junction-to-case (θ_{JC})	- - - - -	See MIL-STD-1835
Thermal resistance, junction-to-ambient (θ_{JA})	- - - - -	90°C/W
Junction temperature (T_J)	- - - - -	+175°C

1.4 Recommended operating conditions.

EIA RS-422 connection, mode voltage	- - - - -	±0.76 V
Supply voltage range (V_{CC})	- - - - -	+4.5 V dc to +5.5 V dc
Supply voltage (V_{EE})	- - - - -	GND
Minimum high-level input voltage (V_{IH})	- - - - -	2.0 V dc
Maximum low-level input voltage (V_{IL})	- - - - -	0.8 V dc
Ambient operating temperature range (T_A)	- - - - -	-55°C to +125°C
EIA RS-423 connection, mode voltage	- - - - -	≥2.0 V
Supply voltage range (V_{CC})	- - - - -	+4.75 V dc to +5.5 V dc
Supply voltage range (V_{EE})	- - - - -	-4.75 V dc to -5.5 V dc
Minimum high-level input voltage (V_{IH})	- - - - -	2.0 V dc
Maximum low-level input voltage (V_{IL})	- - - - -	0.8 V dc
Ambient operating temperature range (T_A)	- - - - -	-55°C to +125°C

^{1/} Must withstand the added P_D due to short circuit test (e.g., I_{SA}/I_{SB}).

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A	REVISION LEVEL B	5962-86721 SHEET 2
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DESC FORM 193A

JUL 94

9004708 0003476 749

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and bulletin. Unless otherwise specified, the following specification, standards, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

SPECIFICATION

MILITARY

MIL-I-38535 - Integrated Circuits (Microcircuits) Manufacturing, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.
MIL-STD-1835 - Microcircuit Case Outlines.

BULLETIN

MILITARY

MIL-BUL-103 - List of Standardized Military Drawings (SMD's).

(Copies of the specification, standards, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-I-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-I-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-I-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) and herein.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table and logic diagram. The truth table and logic diagram shall be as specified on figure 2.

3.3 Electrical performance characteristics. Unless otherwise specified, the electrical performance characteristics are as specified in table I and apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 3

DESC FORM 193A
JUL 94

9004708 0003477 685

TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
EIA RS-422 Connection, mode voltage ≅ 0.76 V <u>1/</u> <u>2/</u>								
Differential output voltage V _{A, B}	V _O	R _L = Infinity	V _{IN} = 2.0 V	1, 2, 3	01		6.0	V
	\overline{V}_O		V _{IN} = 0.8 V				-6.0	
Differential output voltage V _{A, B}	V _T	R _L = 100Ω	V _{IN} = 2.0 V	1, 2, 3	01	2.0		V
	\overline{V}_T		V _{IN} = 0.8 V				-2.0	
Common mode offset voltage	V _{OS} , \overline{V}_{OS}	R _L = 100Ω		1, 2, 3	01		3.0	V
Differential in diff'l output voltage	$ V_T - \overline{V}_T $	R _L = 100Ω		1, 2, 3	01		0.4	V
Differential in common mode offset voltage	$ V_{OS} - \overline{V}_{OS} $	R _L = 100Ω		1, 2, 3	01		0.4	V
V _T - \overline{V}_T	V _{SS}	R _L = 100Ω		1, 2, 3	01	4.0		V
Output voltage common mode range	V _{CMR}	$\overline{V}_{enable} = 2.4$ V <u>3/</u>		1, 2, 3	01	±10		V
Output leakage current	I _{XA}	V _{CC} = 0 V	V _{CMR} = 10 V	1, 2, 3	01		100	μA
	I _{XB}		V _{CMR} = -10 V				-100	
Off-state output current (high impedance)	I _{OX}	V _{CC} = +5.5 V	V _{CMR} = 10 V	1, 2, 3	01		100	μA
			V _{CMR} = -10 V				-100	

See footnotes at end of table.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-86721

REVISION LEVEL
B

SHEET
4

DESC FORM 193A
JUL 94

9004708 0003478 511

TABLE 1. Electrical performance characteristics - continued.

Test	Symbol	Conditions -55°C ≤ T _A ≤ +125°C unless otherwise specified		Group A subgroups	Device type	Limits		Unit
						Min	Max	
Output short circuit current 4/	I _{SA} , I _{SB}	V _{IN} = 2.4 V V _{CC} = +5.5 V	V _{OB} = 6.0 V	1, 2, 3	01	10	150	mA
			V _{OA} = 0 V			-10	-150	
		V _{IN} = 0.4 V V _{CC} = +5.5 V	V _{OB} = 0 V	1, 2, 3	01	-10	-150	
			V _{OA} = 6.0 V			10	150	
Supply current	I _{CC}	V _{IN} = 0.4 V V _{CC} = +5.5 V		1, 2, 3	01		30	mA
Input high voltage	V _{IH}	5/		1, 2, 3	01	2.0		V
Input low voltage	V _{IL}	5/		1, 2, 3	01		0.8	V
Input high current	I _{IH}	V _{CC} = +5.5 V	V _{IN} = 2.4 V	1, 2, 3	01		40	μA
			V _{IN} = 15 V				100	
Input low current	I _{IL}	V _{CC} = +5.5 V	V _{IN} = 0.4 V	1, 2, 3	01		-200	μA
Input clamp voltage	V _{IC}	I _{IN} = -12 mA V _{CC} = +4.5 V		1, 2, 3	01		-1.5	V
Functional tests	FT	See 4.3.1.c		7, 8	01			
Differential output rise and fall time 6/	t _r , t _f	R _L = 100Ω, T _A = 25°C, C _L = 500 pF, V _{CC} = 5.0 V, V _{EE} = GND, See figure 3		9	01		250	ns
Output propagation delay time 6/	t _{PDH} , t _{PDL}	R _L = 100Ω, T _A = 25°C, C _L = 500 pF, V _{CC} = 5.0 V, V _{EE} = GND, See figure 3		9	01		200	ns
Output enable to output time 6/	t _{LZ} , t _{ZH}	R _L = 100Ω, T _A = 25°C, C _L = 500 pF, V _{CC} = 5.0 V, C _C = 0 pF, V _{EE} = GND, See figure 3		9	01		300	ns
	t _{HZ} , t _{ZL}						350	

See footnotes at end of table.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-86721

REVISION LEVEL
B

SHEET
5

DESC FORM 193A

JUL 94

9004708 0003479 458

TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
EIA RS-423 connection, mode voltage ≥2.0 V								
Output voltage	V _O	R _L = Infinity V _{CC} = V _{EE} = 4.75 V	V _{IN} = 2 V	1, 2	01	4.0	6.0	V
				3		3.9	6.0	
	V _O		V _{IN} = 0.4 V	1, 2	01	-4.0	-6.0	
				3		-3.9	-6.0	
Output voltage 7/	V _T	R _L = 450Ω, V _{CC} = V _{EE} = 4.75 V	V _{IN} = 2.4 V	1, 2, 3	01	3.6		V
	V _T		V _{IN} = 0.4 V				-3.6	
Output unbalance 7/	V _T - V _T	R _L = 450Ω, V _{CC} = V _{EE}		1, 2, 3	01		0.4	V
Output leakage power off	I _{X+}	V _{CC} = V _{EE} = 0 V	V _{OUT} = 6.0 V	1, 2, 3	01		100	μA
	I _{X-}		V _{OUT} = -6.0 V				-100	
Output short circuit current 4/	I _{S+}	V _{OUT} = 0 V, V _{CC} = 5.5 V, V _{EE} = -5.5 V	V _{IN} = 2.4 V	1, 2, 3	01	-20	-150	μA
	I _{S-}		V _{IN} = 0.4 V				20	
Positive supply current	I _{CC}	V _{IN} = 0.4 V, R _L = Infinity V _{CC} = V _{EE} = 5.5 V		1, 2, 3	01		30	mA
Negative supply current	I _{EE}	V _{IN} = 0.4 V, R _L = Infinity V _{CC} = V _{EE} = 5.5 V		1, 2, 3	01		-22	mA
Input clamp voltage	V _{IC}	I _{IN} = -12 mA, V _{CC} = +4.75 V V _{EE} = -5.5 V		1, 2, 3	01		-1.5	V
Input high voltage	V _{IH}	9/		1, 2, 3	01	2.0		V
Input low voltage	V _{IL}	9/		1, 2, 3	01		0.8	V

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 6

DESC FORM 193A
JUL 94

9004708 0003480 17T

TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions -55°C ≤ T _A ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
Input high current	I _{IH}	V _{CC} = V _{EE} = 5.5 V, V _{IN} = 2.4 V	1, 2, 3	01		40	μA	
						100		
Input low current	I _{IL}	V _{CC} = V _{EE} = 5.5 V, V _{IN} = 0.4 V	1, 2, 3	01		-200	μA	
Functional tests	FT	See paragraph 4.3.1.c	7, 8	01				
Rise and fall time	t _r , t _f	R _L = 450Ω, C _L = 500 pF, C _C = 0 pF, See figure 3	T _A = 25°C, V _{CC} = 5.0 V, V _{EE} = -5.0 V	9	01		300	ns
			V _{CC} = +4.75 V to +5.5 V	10, 11			375	
			V _{EE} = -4.75 V to -5.5 V	6/				
Output propagation delay time	t _{PDH} , t _{PDL}	R _L = 450Ω, C _L = 500 pF, C _C = 0 pF, See figure 3	T _A = 25°C, V _{CC} = 5.0 V, V _{EE} = -5.0 V	9	01		300	ns
			V _{CC} = +4.75 V to +5.5 V	10, 11			375	
			V _{EE} = -4.75 V to -5.5 V	6/				

- 1/ R_L connected between each output and its complement.
- 2/ Measurements for ATE loads are for single-ended conditions.
- 3/ V_{CMR} is guaranteed by tested parameters I_{XA}, I_{XB} and I_{OX}.
- 4/ Not more than one output should be shorted at a time. Duration of short circuit test should not exceed one second.
- 5/ Input thresholds are tested during DC tests and may be done in combination with testing of other DC parameters.
- 6/ This parameter is guaranteed, but not tested.
- 7/ This parameter is tested by forcing an equivalent current.
- 8/ The V_{IC} parameter in the RS423 mode is guaranteed by the tested V_{IC} parameter in the RS422 mode.
- 9/ Input thresholds are tested during DC tests and may be done in combination with testing of other DC parameters.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 7

DESC FORM 193A
JUL 94

9004708 0003481 006

Device type	01	
Case outline	E, F	2
Terminal number	Terminal symbol	
1	V _{CC}	NC
2	INPUT A	V _{CC}
3	INPUT/ENABLE B	INPUT A
4	MODE	INPUT/ENABLE B
5	GND	MODE
6	INPUT/ENABLE C	NC
7	INPUT D	GND
8	V _{EE}	INPUT/ENABLE C
9	SLEW RATE CONTROL D	INPUT D
10	OUTPUT D	V _{EE}
11	OUTPUT C	NC
12	SLEW RATE CONTROL C	SLEW RATE CONTROL D
13	SLEW RATE CONTROL B	OUTPUT D
14	OUTPUT B	OUTPUT C
15	OUTPUT A	SLEW RATE CONTROL C
16	SLEW RATE CONTROL A	NC
17	---	SLEW RATE CONTROL B
18	---	OUTPUT B
19	---	OUTPUT A
20	---	SLEW RATE CONTROL A

FIGURE 1. Terminal connections.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 8

DESC FORM 193A
JUL 94

9004708 0003482 T42

Mode	Inputs		Outputs	
	A(D)	B(C)	A(D)	B(C)
0	0	0	0	1
0	0	1	Z	Z
0	1	0	1	0
0	1	1	Z	Z
1	0	0	0	0
1	0	1	0	1
1	1	0	1	0
1	1	1	1	1

0 = low level
 1 = high level
 Z = high impedance

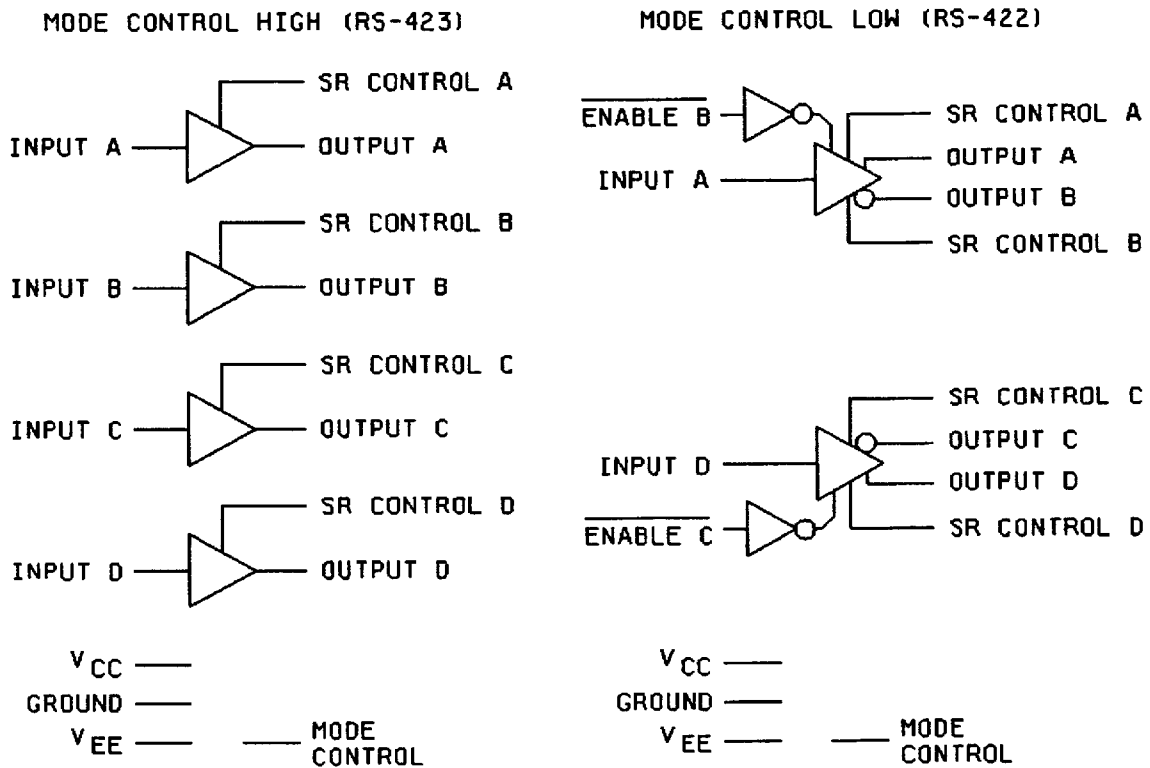


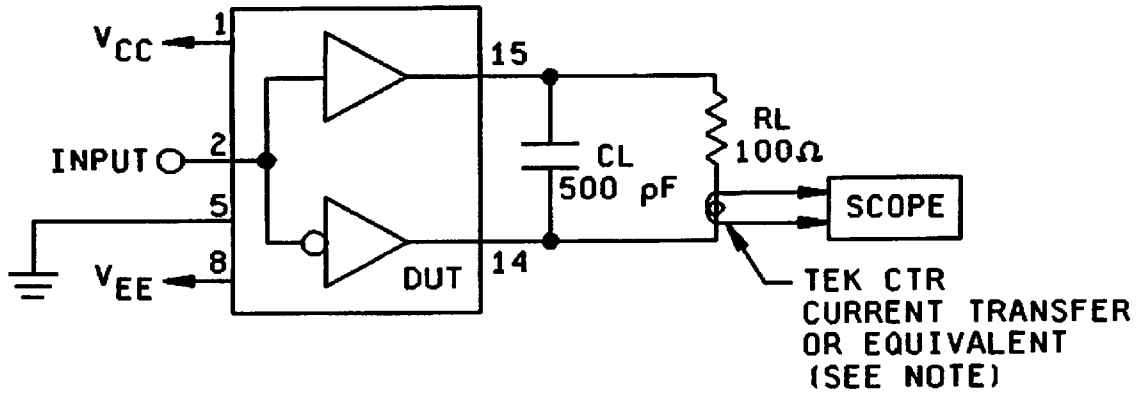
FIGURE 2. Truth table and logic diagram.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 9

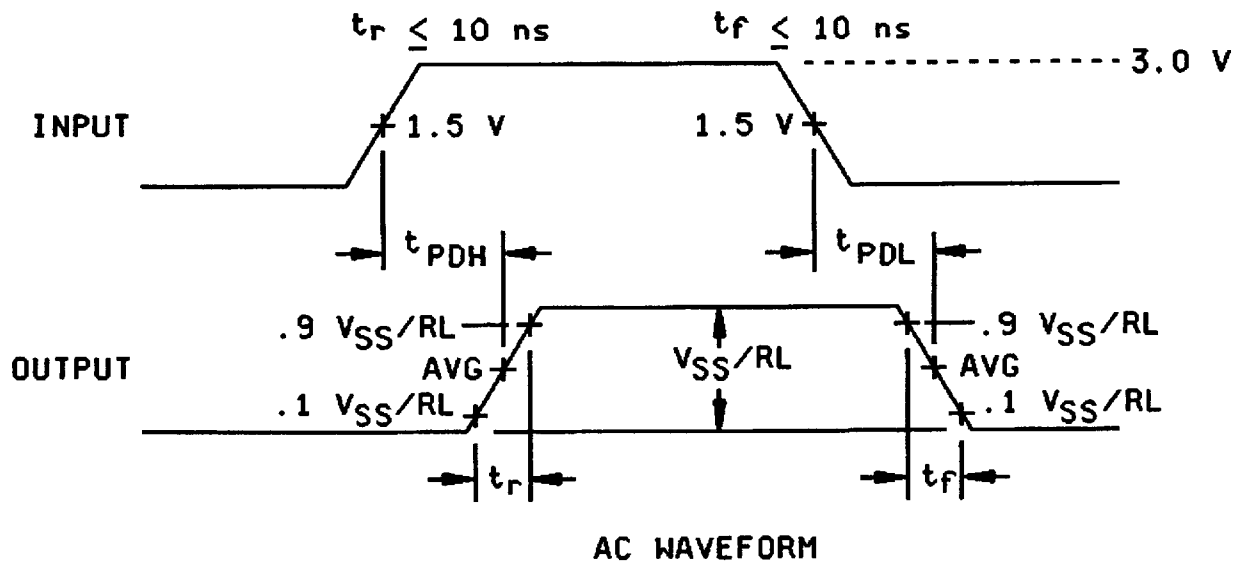
DESC FORM 193A
 JUL 94

9004708 0003483 989

MODE CONTROL LOW
RS-422



TEST CIRCUIT



AC WAVEFORM

NOTE: Current probe is the easiest way to display a differential waveform.

FIGURE 3. AC test circuits and waveforms.

STANDARD
MICROCIRCUIT DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A

5962-86721

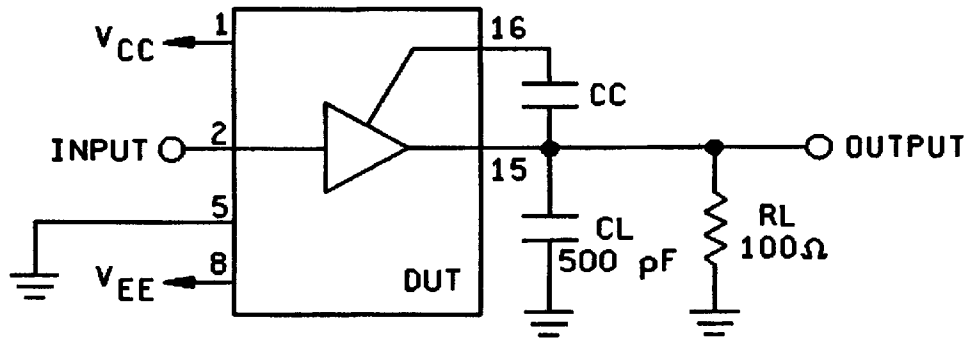
REVISION LEVEL
B

SHEET
10

DESC FORM 193A
JUL 94

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MODE CONTROL HIGH
RS-422



TEST CIRCUIT

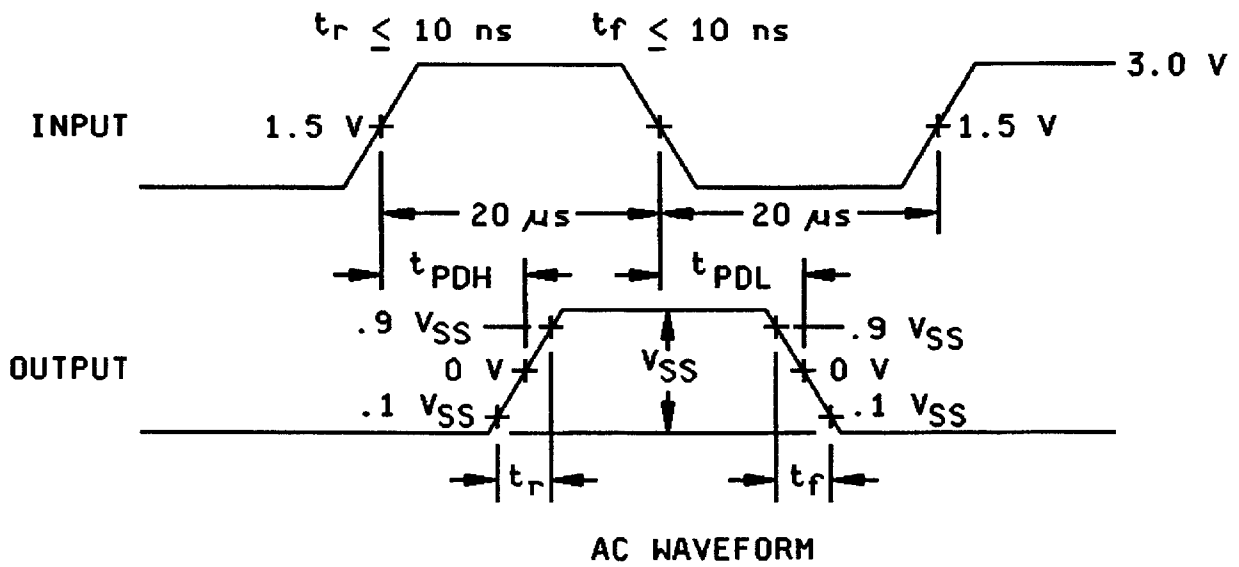


FIGURE 3. AC test circuits and waveforms - continued.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 11

DESC FORM 193A
JUL 94

9004708 0003485 751

THREE STATE OUTPUT
RS-422

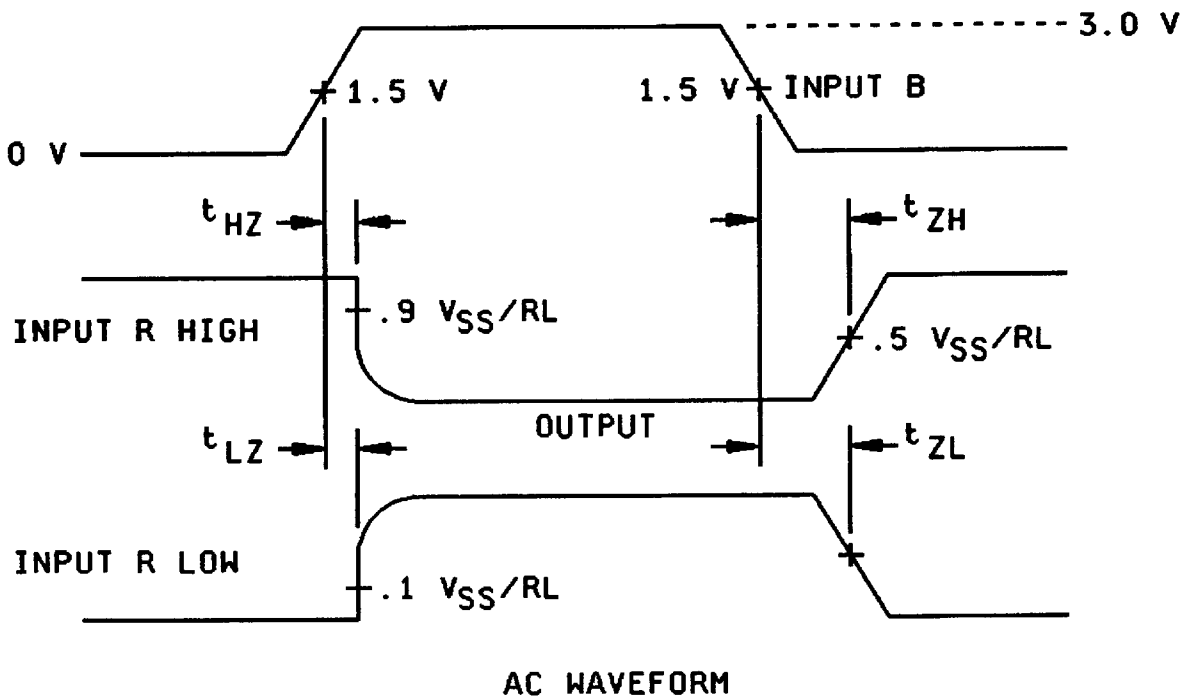
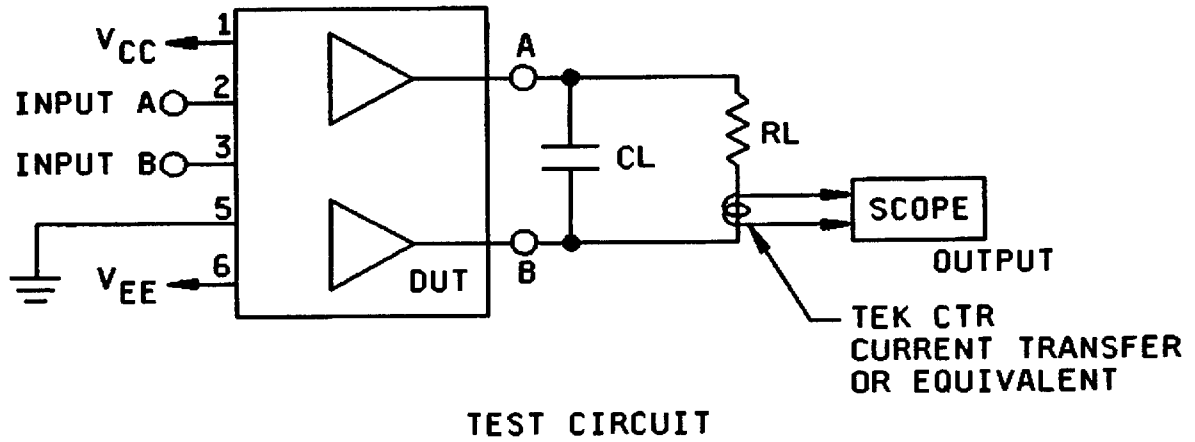


FIGURE 3. AC test circuits and waveforms - continued.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 12

DESC FORM 193A
JUL 94

9004708 0003486 698

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DESC-EC shall be required in accordance with MIL-STD-883 (see 3.1 herein).

3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein).

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.

(2) $T_A = +125^\circ\text{C}$, minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

a. Tests shall be as specified in table II herein.

b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.

c. Subgroups 7 and 8 shall include verification of the truth table.

4.3.2 Groups C and D inspections.

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test conditions, method 1005 of MIL-STD-883.

(1) Test condition A, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.

(2) $T_A = +125^\circ\text{C}$, minimum.

(3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 13

DESC FORM 193A

JUL 94

■ 9004708 0003487 524 ■

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with method 5005, table I)
Interim electrical parameters (method 5004)	- - -
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10**, 11**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

** Subgroups 10 and 11, if not tested, shall be guaranteed to the limits specified in table I.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein).

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal .

6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.

6.5 Comments. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

STANDARD MICROCIRCUIT DRAWING DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444	SIZE A		5962-86721
		REVISION LEVEL B	SHEET 14

DESC FORM 193A

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